



FIG 3



FIG 4



FIG 5

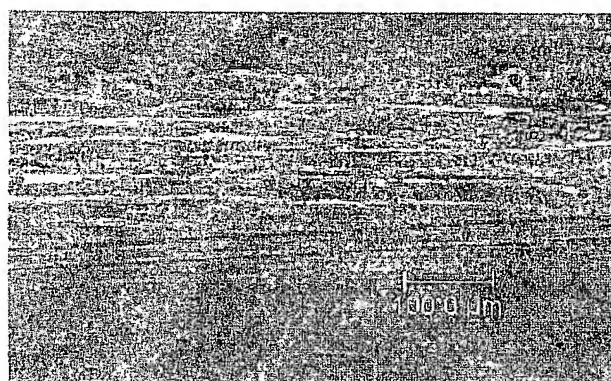


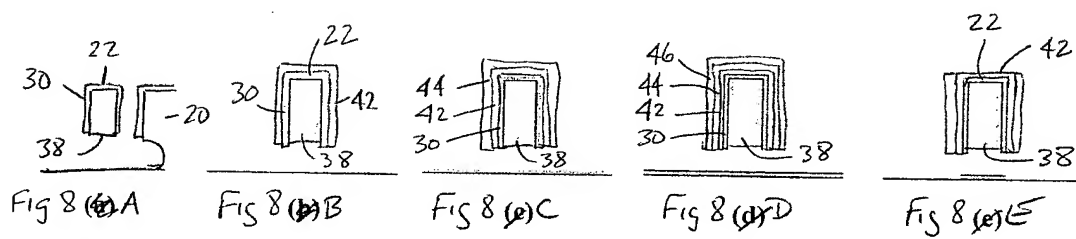
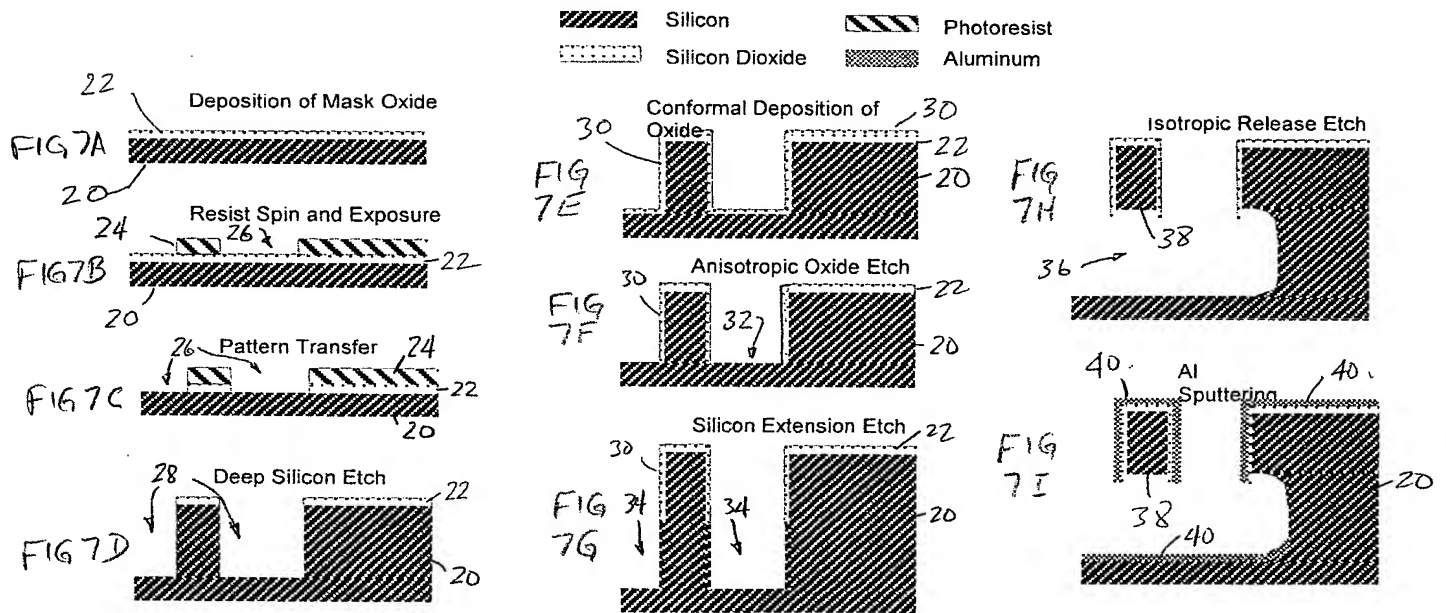
FIG 6



FIG 1



FIG 2



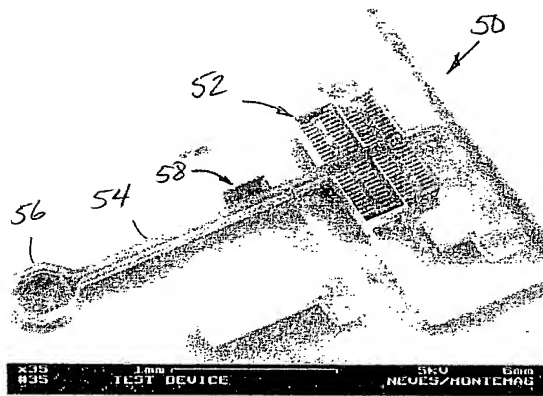


Fig 9(a)A

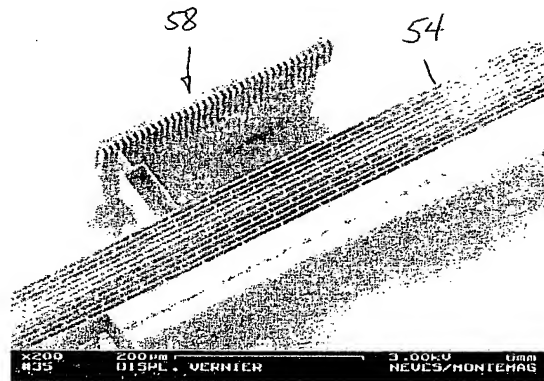


Fig 9(b)B

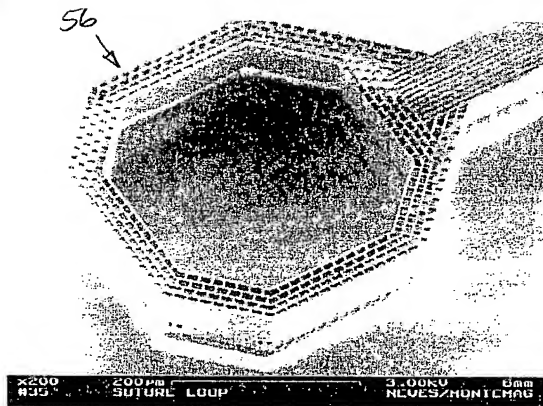


Fig 9(c)C

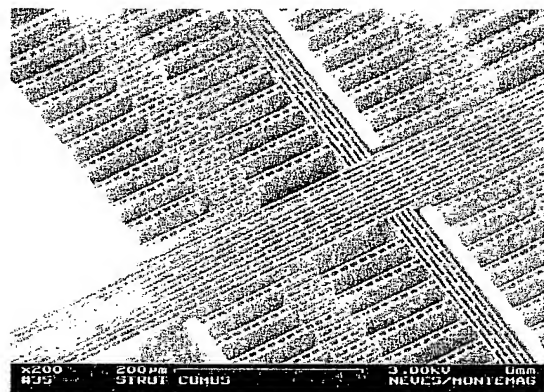
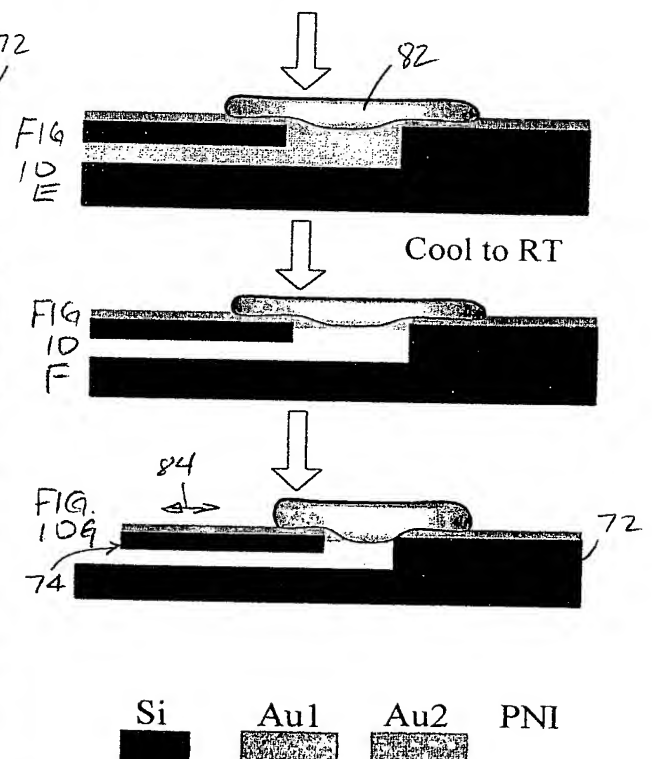
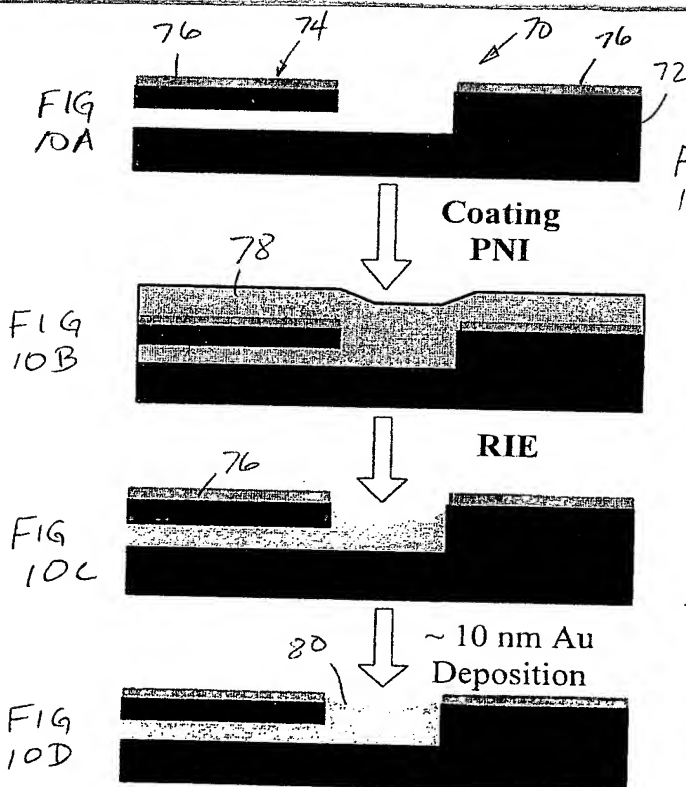


Fig 9(d)D



1. Si(111) wafer with surface SiO_2 104
 A. 102
 2. Fabricate cantilever with the SCREAM process 100
 B. 100
 3. Coat with 5% PNIPAAm/ethanol and evaporation until dry at room 108
 C. 108
 4. Etch PNIPAAm through a shadow mask 110
 D. 110
 5. Deposit Cr/Au film 112
 E. 112
 6. Remove shadow mask. 114
 F. 114

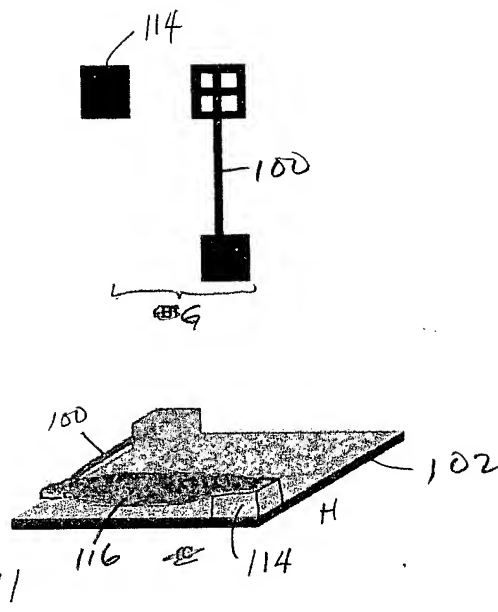


FIG 11

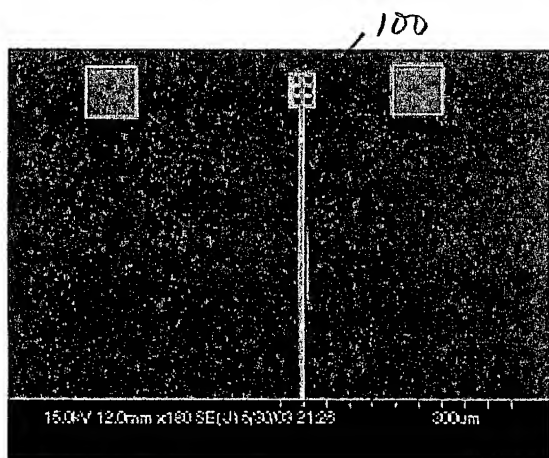


FIG 12 (A)

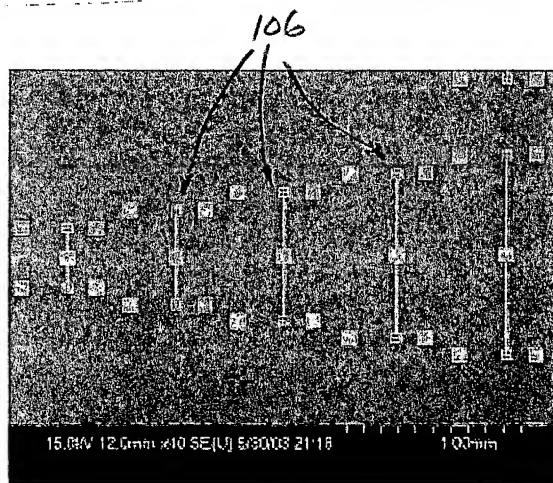


FIG 12 (B)

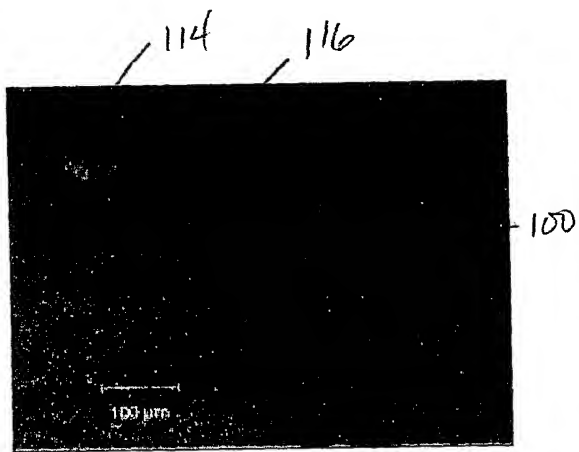


FIG 13A)

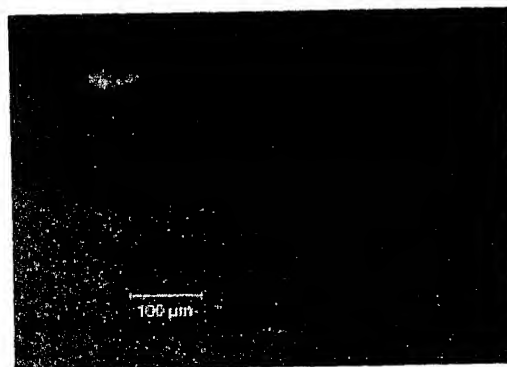


FIG 13B)

FIG
14

